Title (en)

SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING WIRE BOND INTERCONNECTION BETWEEN STACKED PACKAGES

Title (de)

HALBLEITER-MEHRFACHKAPSELUNGSMODUL MIT DRAHTBONDVERBINDUNG ZWISCHEN GESTAPELTEN KAPSELUNGEN

Title (fr)

MODULE MULTI-BOITIER A SEMI-CONDUCTEURS COMPORTANT UNE INTERCONNEXION DE MICROCABLAGES ENTRE DES BOITIERS

Publication

EP 1547141 A4 20100224 (EN)

Application

EP 03754585 A 20030915

Priority

- US 0328919 W 20030915
- US 41159002 P 20020917
- US 63254903 A 20030802
- US 63256803 A 20030802
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- US 63255003 A 20030802
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Abstract (en)

[origin: WO2004027823A2] A semiconductor multi-package module having stacked lower and upper packages, each package including a die attached to a substrate, in which the upper and lower substrates are interconnected by wire bonding. Also, a method for making a semiconductor multi-package module, by providing a lower molded package including a lower substrate and a die, affixing an upper molded package including an upper substrate onto the upper surface of the lower package, and forming z-interconnects between the upper and lower substrates.

IPC 8 full level

H01L 23/12 (2006.01); **H01L 25/065** (2006.01); **H01L 25/10** (2006.01); **H01L 25/11** (2006.01); **H01L 25/18** (2006.01)

CPC (source: EP KR)

H01L 23/538 (2013.01 - KR); **H01L 23/552** (2013.01 - EP); **H01L 25/03** (2013.01 - EP); **H01L 25/105** (2013.01 - EP); H01L 24/48 (2013.01 - EP); H01L 24/73 (2013.01 - EP); H01L 2224/056 (2013.01 - EP); H01L 2224/16 (2013.01 - EP); H01L 2224/16225 (2013.01 - EP); H01L 2224/32225 (2013.01 - EP); H01L 2224/45015 (2013.01 - EP); H01L 2224/45099 (2013.01 - EP); H01L 2224/48091 (2013.01 - EP); H01L 2224/48227 (2013.01 - EP); H01L 2224/48465 (2013.01 - EP); H01L 2224/73204 (2013.01 - EP); H01L 2224/73253 (2013.01 - EP); H01L 2224/73265 (2013.01 - EP); H01L 2224/854 (2013.01 - EP); H01L 2224/8592 (2013.01 - EP); H01L 2225/06568 (2013.01 - EP); H01L 2225/1023 (2013.01 - EP); H01L 2225/1052 (2013.01 - EP); H01L 2225/1058 (2013.01 - EP); H01L 2225/1094 (2013.01 - EP); H01L 2924/00014 (2013.01 - EP); H01L 2924/01079 (2013.01 - EP); H01L 2924/12041 (2013.01 - EP); H01L 2924/15311 (2013.01 - EP); H01L 2924/1532 (2013.01 - EP); H01L 2924/15321 (2013.01 - EP); H01L 2924/15331 (2013.01 - EP); H01L 2924/16152 (2013.01 - EP); H01L 2924/181 (2013.01 - EP); H01L 2924/19107 (2013.01 - EP); H01L 2924/3025 (2013.01 - EP)

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DOCDB simple family (publication)

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